

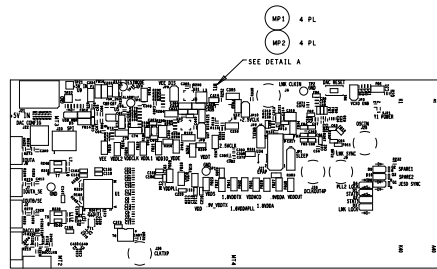
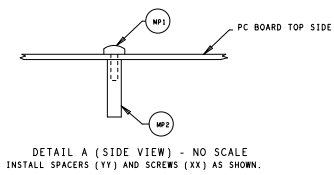
8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

THIS DRAWING IS INTENDED TO HELP IN THE ASSEMBLY OF THE DESIGN.

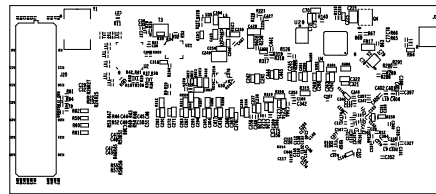
1. REFER TO ODB++ FILE FOR SPECIFIC COMPONENT LOCATION INFORMATION.
2. USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY.
RoHS COMPLIANT AND LEAD FREE.
3. MARK BOARD'S SILKSCREEN AND ESD BAG WITH THE APPROPRIATE EVM PART NUMBER.
4. IPC-A-610 / ACCEPTABILITY OF ELECTRONIC ASSEMBLIES, CLASS 2, CURRENT REVISION.
5. SEE HEATSINK SPEC DRAWING FOR INSTALLATION REFERENCE.

REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

D
C
B
A



TOP VIEW



BOTTOM VIEW

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	ASSEMBLY DRAWING DAC38RF8xEVM	
MATERIAL	DRAWN L. NGUYEN	03-07-16		
SEE NOTE 5	ENGR E. DWOBENG	03-07-16	SIZE	CODE IDENT NO.
FINISH	SEE NOTES 7, 8, 9		B	
DO NOT SCALE DRAWING			SCALE	NONE
				DRAWING NO.
				REV. E
				SHEET 1 OF 1

8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

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